Specification for Approval

Customer:_____

Model Name:_____

Supplier Approval			Customer approval
R&D Designed	R&D Approved	QC Approved	
Peter	Peng Jun		

Revision Record

REV NO.	REV DATE	CONTENTS	Note
A	2015-03-21	NEW ISSUE	

Table of Contents

1. Scope

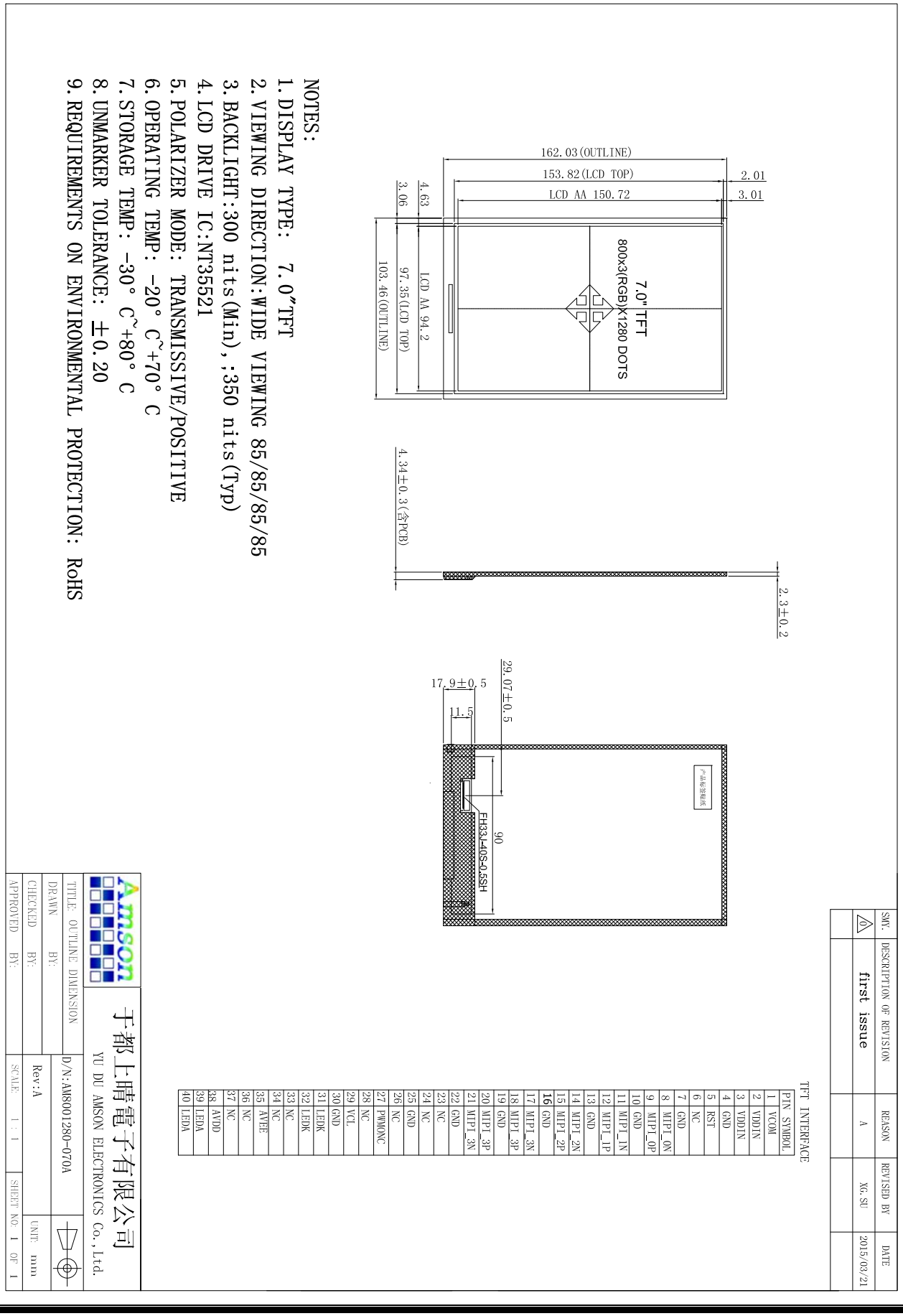
This specification defines general provisions as well as inspection standards for TFT module supplied by AMSON electronics.

If the event of unforeseen problem or unspecified items may occur, naturally shall negotiate and agree to solution.

2. General Information

ITEM	STANDARD VALUES	UNITS
LCD type	7.0”TFT	--
Dot arrangement	800×3(RGB)×1280	dots
Color filter array	RGB vertical stripe	--
Display mode	Normally White(IPS)	--
Viewing Direction	85/85/85/85	--
Driver IC	NT35521	--
Module size	103.46(W)×162.03(H)×2.30(T)	mm
Active area	94.20(W)×150.72(H)	mm
Dot pitch	0.03925(W)×0.1177(H)	mm
Interface	MIPI	--
Operating temperature	-20 ~ +70	°C
Storage temperature	-30 ~ +80	°C
Back Light	20White LED	--
Brightness	300 cd/m^2(Min);350 cd/m^2 (Typ)	
Module Weight	TBD	g

3. External Dimensions



4. Interface Description

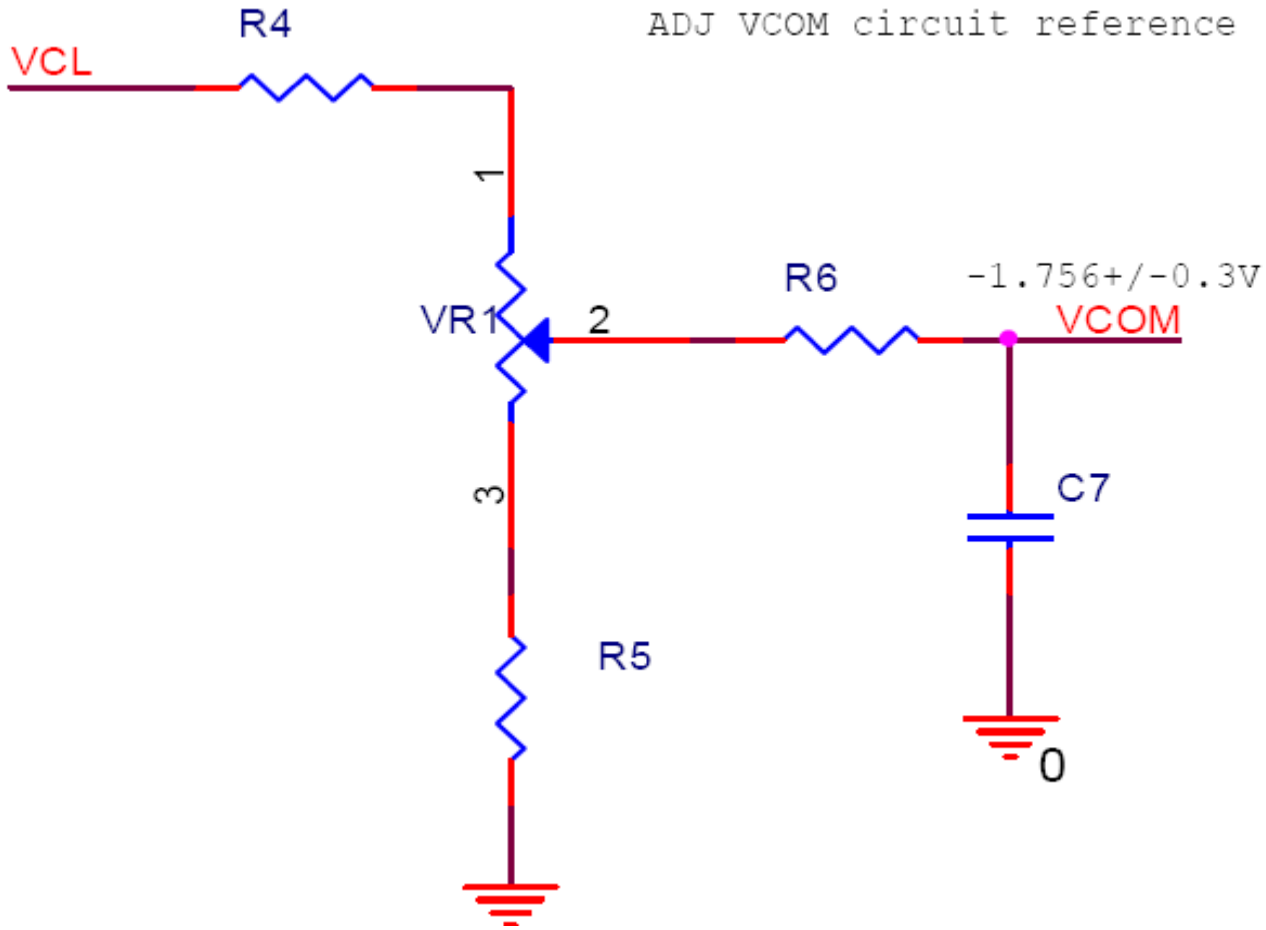
A 40pin connector is used for the module electronics interface. In this model used "FH33J-40S-0.5SH(10)" manufactured by Hirose or the same package connector.

PIN NO.	PIN NAME	DESCRIPTION
1	VCOM	Common Voltage(-1.756+/-0.3V)
2	VDDIN	Power supply for interface system except MIPI interface pin ,VDDIN=3.3V
3	VDDIN	
4	GND	GROUND
5	RST	Device reset signal
6	NC	No connection
7	GND	GROUND
8	MIPI_0N	MIPI Negative data signal(-)
9	MIPI_0P	MIPI Positive data signal(+)
10	GND	GROUND
11	MIPI_1N	MIPI Negative data signal(-)
12	MIPI_1P	MIPI Positive data signal(+)
13	GND	GROUND
14	MIPI_CKN	MIPI Negative clock signal(-)
15	MIPI_CKP	MIPI Positive clock signal(+)
16	GND	GROUND
17	MIPI_2N	MIPI Negative data signal(-)
18	MIPI_2P	MIPI Positive data signal(+)
19	GND	GROUND
20	MIPI_3N	MIPI Negative data signal(-)
21	MIPI_3P	MIPI Positive data signal(+)
22	GND	GROUND
23	NC	No connection
24	NC	No connection
25	GND	GROUND
26	NC	No connection
27	PWMO	PWM control signal for LED driver(CABC)
28	NC	No connection
29	VCL	Output voltage pin ,use it to generate Vcom voltage by a VR circuit(output voltage-2.5v)
30	GND	GROUND
31	LEDK	The cathode of LED power
32	LEDK	The cathode of LED power
33	NC	No connection
34	NC	No connection
35	AVEE	Analog supply positive voltage
36	NC	No connection

37	NC	No connection
38	AVDD	Analog supply positive voltage
39	LEDA	The Anode of LED power
40	LEDA	The Anode of LED power

Input, O: output, P: Power

Note1: Typical VCOM is only a reference value, it must be optimized according to each LCM, Be sure to use VR



Note2: Global reset pin Active Low to enter Reset State. Normally pull high. Suggest to connecting within RC reset circuit for stability.

5. Operation Specifications

5.1. Absolute Maximum Ratings

Item	Symbol	Min.	Max.	Unit
Power voltage	VDDIN	-0.3	5.5	V
	AVDD	-0.3	6.6	V
	AVEE	+0.3	-6.6	V
Operating Temperature	TOP	-20	70	°C
Storage Temperature	TST	-30	80	°C
Storage Humidity	HD	20	90	%RH

Note 1: The absolute maximum rating values of this product are not allowed to be exceeded at any times. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.

5.2. Operation Conditions

Item	Symbol	Min.	Typ.	Max.	Unit	Remark
Power voltage	VDDIN	3.0	3.3	3.6	Power voltage	VDDIN
	AVDD	5.2	(5.8)	6.0		AVDD
	AVEE	-6.0	(-5.8)	-5.2		AVEE
Input logic High Voltage	V_{IH}	0.7VDDIN	-	VDDIN	Input logic	
Input logic Low Voltage	V_{IL}	0	-	0.3VDDIN	Input logic	

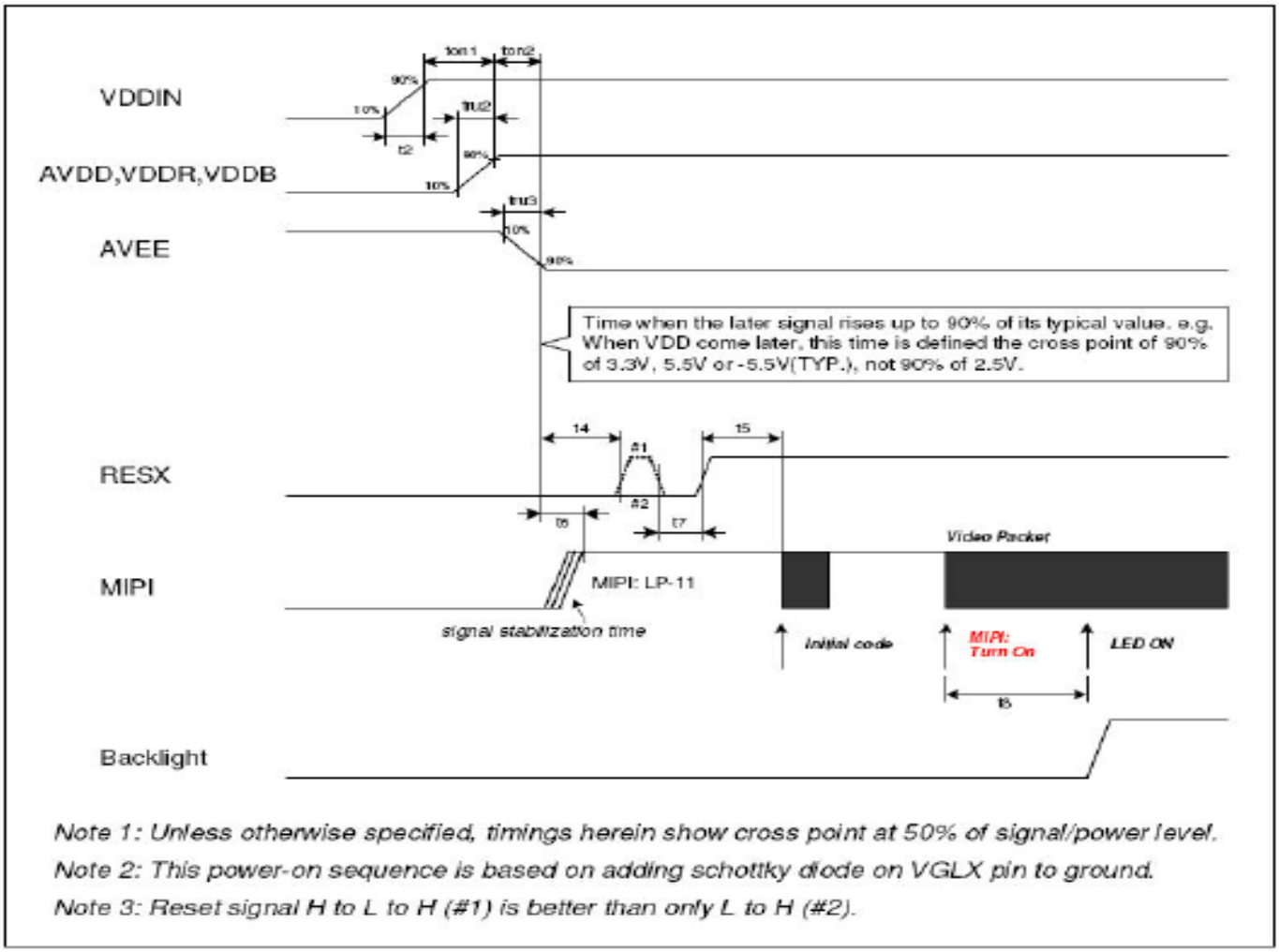
5.3. Current Consumption

(GND =0V)

Item	Symbol	Values			Unit	Remark
		Min	Typ	Max		
Current for Driver	IVDDIN	-	(35)	-	mA	
	IAVDD	-	(35)	-	mA	
	IAVEE	-	(35)	-	mA	

6. Power Sequence

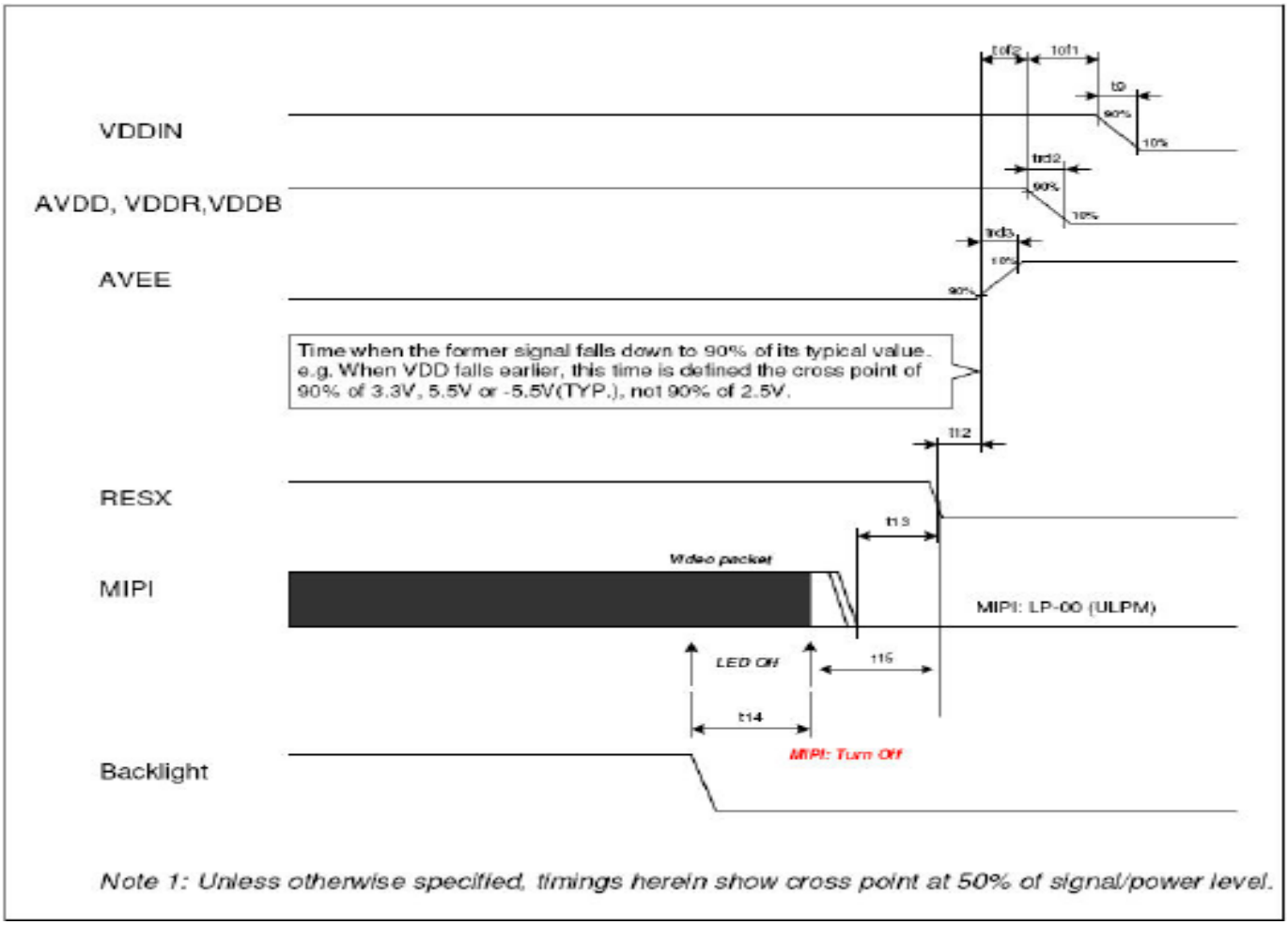
a. Power on:



Note 1: Unless otherwise specified, timings herein show cross point at 50% of signal/power level.
Note 2: This power-on sequence is based on adding schottky diode on VGLX pin to ground.
Note 3: Reset signal H to L to H (#1) is better than only L to H (#2).

Symbol	Value			Unit	Remark
	Min.	Typ.	Max.		
ton1		No limit		ms	
ton2		0(Note)		ms	
ton3		No limit	-	ms	
ton4		No limit	-	ms	
t2			150	µs	
tru1			150	µs	
tru2			150	µs	
tru3			150	µs	
tru4			150	µs	
t4	40	-	-	ms	

b. Power off:



Note 1: Unless otherwise specified, timings herein show cross point at 50% of signal/power level.

Symbol	Value			Unit	Remark
	Min.	Typ.	Max.		
t9	150			μs	
tof1		No limit		ms	
tof2		0(Note)	-	ms	
tof3		No limit	-	ms	
tof4		No limit		ms	
trd1	150			μs	
trd2	150			μs	
trd3	150			μs	
trd4	150			μs	
t12	0		-	ms	
t13	0			ms	
T14	0			ms	
T15	10			ms	

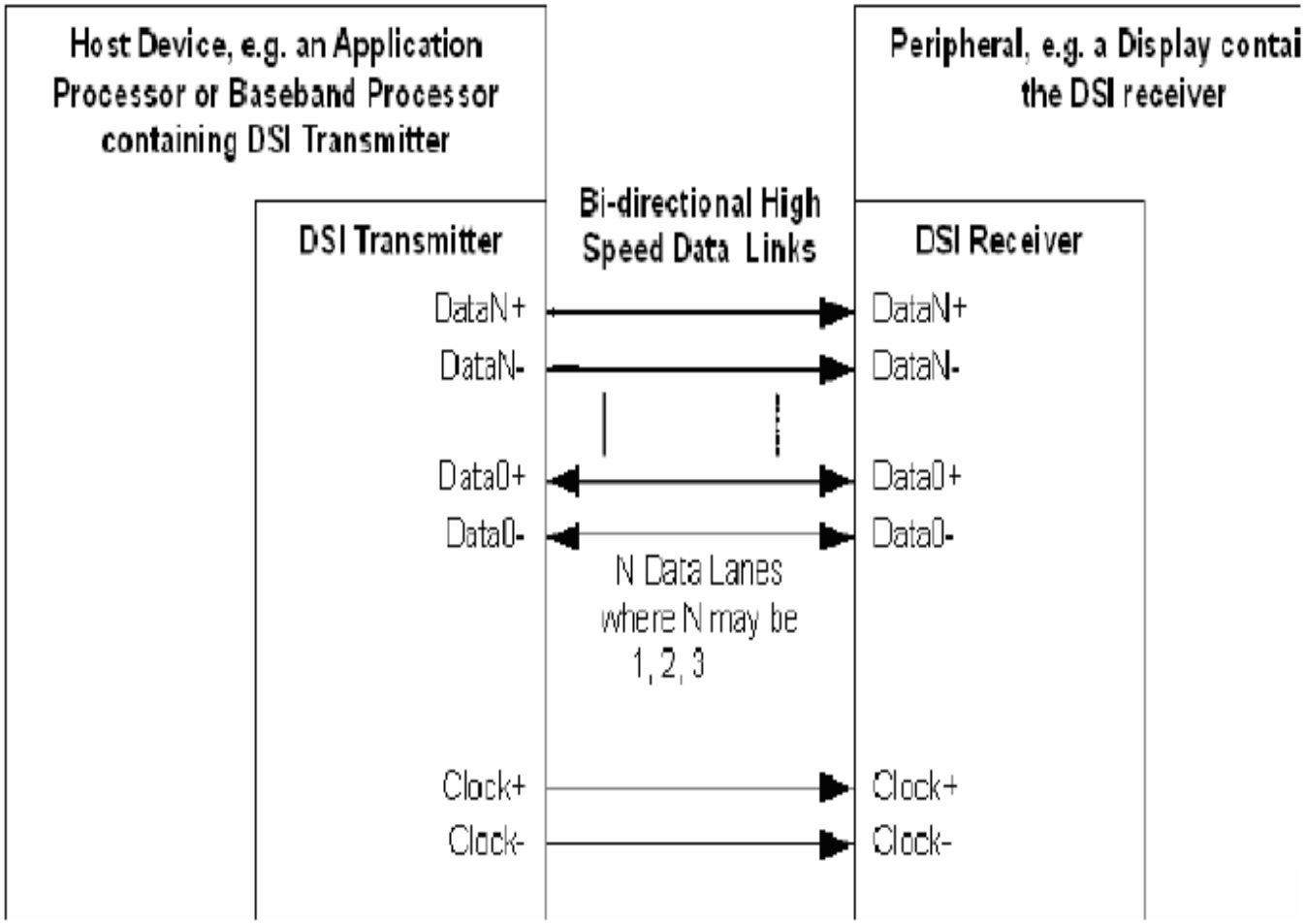
7. Timing Characteristics

7.1. MIPI interface (Mobile Industry Processing Interface)

MIPI Lane Configuration

	MCU (Master) Display Module (Slave)
Clock Lane+/-	Unidirectional Lane ■ Clock Only ■ Escape Mode(ULPS Only)
Data Lane0+/-	Bi-directional Lane ■ Forward High-Speed ■ Bi-directional Escape Mode ■ Bi-directional LPDT
Data Lane1+/-	Unidirectional ■ Forward High speed
Data Lane2+/-	Unidirectional ■ Forward High speed
Data Lane3+/-	Unidirectional ■ Forward High speed

The connection between host device and display module is as reference



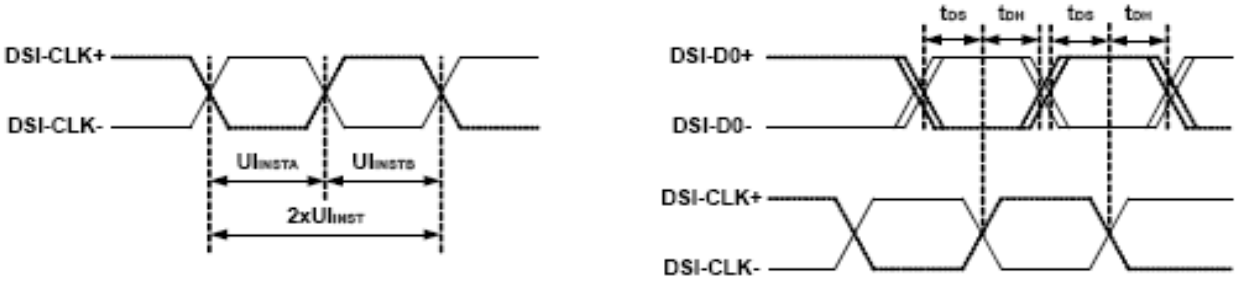
7. MIPI signal Timing Characteristics

7.2.1. AC Electrical Characteristics

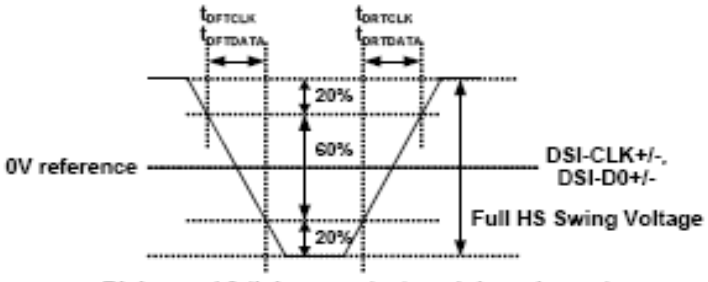
High Speed Mode

Signal	Symbol	Parameter	MIN	TYP	MAX	Unit	Description
DSI-CLK+/-	2xUIINST	Double UI instantaneous	4	-	8	ns	4 Lane (Note 2)
			3	-	8	ns	3 Lane (Note 2)
			2.352	-	8	ns	2 Lane (Note 3)
DSI-CLK+/-	UIINSTA UIINSTB	UI instantaneous halfs (UI = UIINSTA = UIINSTB)	2	-	4	ns	4 Lane (Note 2)
			1.5	-	4	ns	3 Lane (Note 2)
			1.176	-	4	ns	2 Lane (Note 3)
DSI-Dn+/-	tDS	Data to clock setup time	0.15x UI	-	-	ps	
DSI-Dn+/-	tDH	Data to clock hold time	0.15x UI	-	-	ps	
DSI-CLK+/-	tDRTCLK	Differential rise time for clock	150	-	0.3xUI	ps	
DSI-Dn+/-	tDRTDATA	Differential rise time for data	150	-	0.3xUI	ps	
DSI-CLK+/-	tDFTCLK	Differential fall time for clock	150	-	0.3xUI	ps	
DSI-Dn+/-	tDFTDATA	Differential fall time for data	150	-	0.3xUI	ps	

Note 1) Dn = D0, D1, D2 and D3.
Note 2) Maximum total bit rate is 2Gbps for 24-bit data format, 1.5Gbps for 18-bit data format and 1.33Gbps for 16-bit data format in 3 lanes or 4 lanes application which support to 800RGBx 1280 resolution.
Note 3) Maximum total bit rate is 1.7Gbps for 24-bit data format, 1.275Gbps for 18-bit data format and 1.13Gbps for 16-bit data format in 2 lanes application which support to 720RGBx1280 resolution.



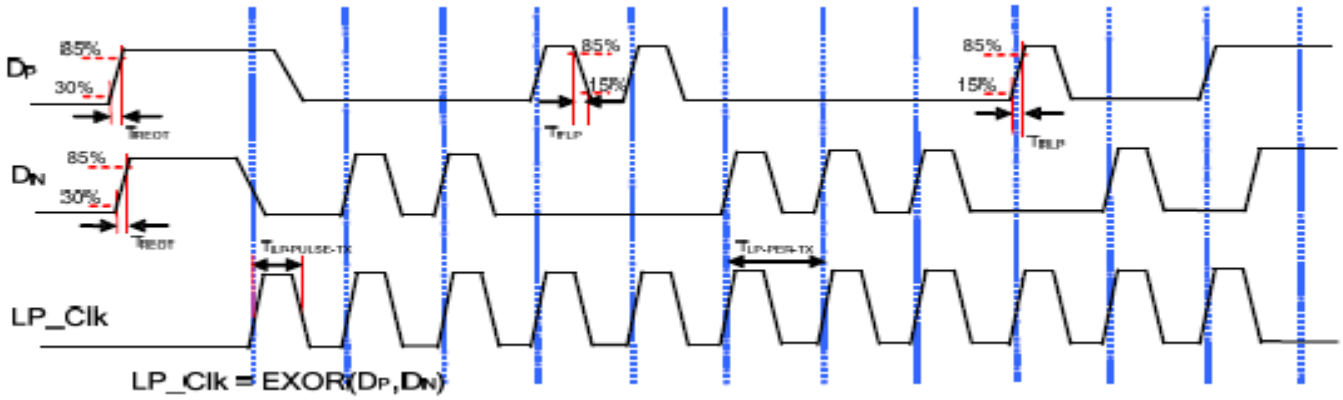
DSI clock channel timing



Rising and fall time on clock and data channel

LP Transmission

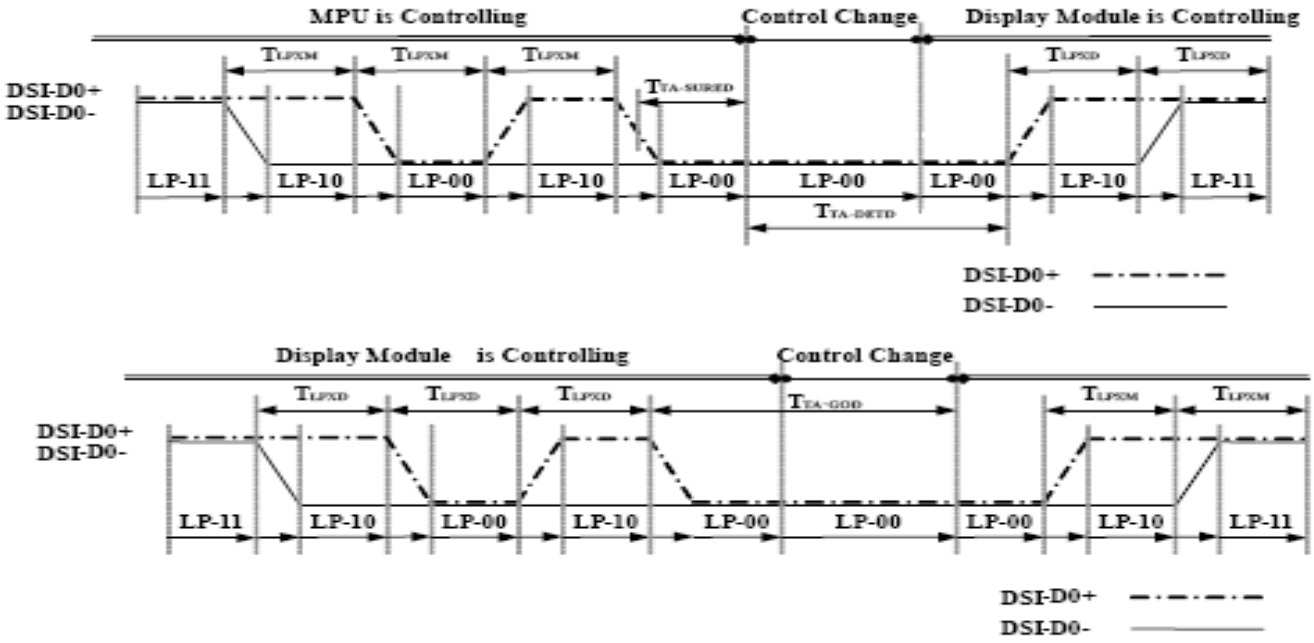
Parameter	Symbol	Values			Unit	Remark
		Min.	Typ.	Max.		
DSI CLK frequency(LP)	F_{DSICLK_LP}			10	MHz	
DSI CLK Cycle Time(LP)	t_{CLKC_LP}	100			ns	
DSI Data Transfer Rate(LP)	t_{DSIR_LP}			10	Mbps	
15%-85% rise time and fall time	T_{RLP} / T_{FLP}	-	-	35	ns	
30%-85% rise time(from HS to LP)	T_{REOT}	-	-	35	ns	
Pulse width of the LP exclusive-OR clock	$t_{LP-PULSE-TX}$	50	65	-	ns	
Period of the LP exclusive-OR clock	$t_{LP-PRE-TX}$	100	130	-	ns	



Low Power Mode

Signal	Symbol	Parameter	MIN	TYP	MAX	Unit	Description
DSI-D0+ /-	TLPXM	Length of LP-00, LP-01, LP-10 or LP-11 periods MPU (Display Module	50	-	75	ns	Input
DSI-D0+ /-	TLPXD	Length of LP-00, LP-01, LP-10 or LP-11 periods Display Module (MPU	50	-	75	ns	Output
DSI-D0+ /-	TTA-SURED	Time-out before the MPU start driving	TLPXD	-	2xTLPXD	ns	Output
DSI-D0+ /-	TTA-GETD	Time to drive LP-00 by display module	5xTLPXD	-	-	ns	Input
DSI-D0+ /-	TTA-GOD	Time to drive LP-00 after turnaround request - MPU	4xTLPXD	-	-	ns	Output

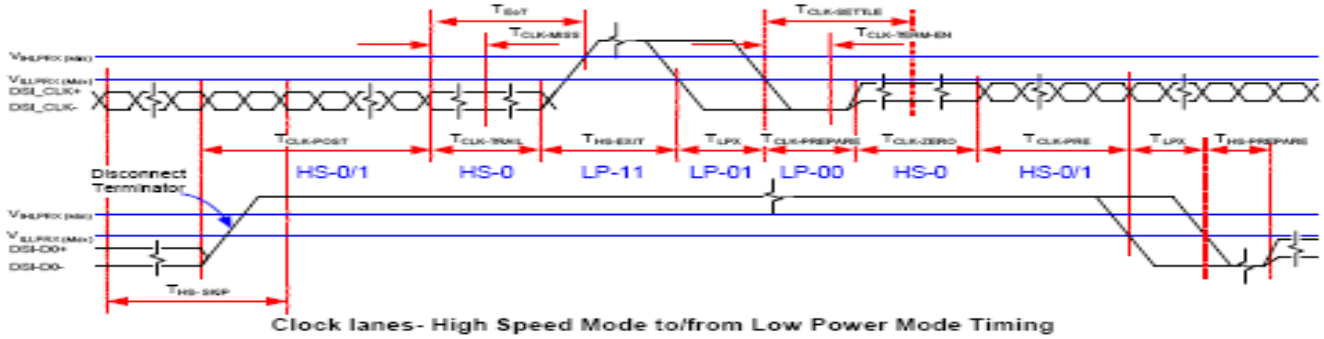
Bus Turnaround (BAT) from MPU to display module Timing



Bus Turnaround (BAT) from display module to MPU Timing

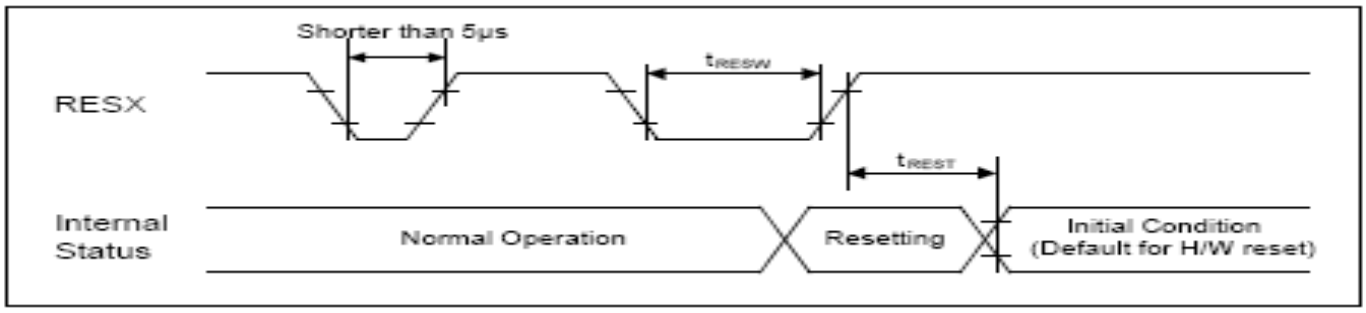
DSI Bursts

Signal	Symbol	Parameter	MIN	TYP	MAX	Unit	Description
Low Power Mode to High Speed Mode Timing							
DSI-Dn+/-	TLPX	Length of any low power state period	50	-	-	ns	Input
DSI-Dn+/-	THS-PREPARE	Time to drive LP-00 to prepare for HS transmission	40+4xUI	-	85+6xUI	ns	Input
DSI-Dn+/-	THS-TERM-EN	Time to enable data receiver line termination measured from when Dn crosses VILMAX	-	-	35+4xUI	ns	Input
High Speed Mode to Low Power Mode Timing							
DSI-Dn+/-	THS-SKIP	Time-out at display module to ignore transition period of EoT	40	-	55+4xUI	ns	Input
DSI-Dn+/-	THS-EXIT	Time to drive LP-11 after HS burst	100	-	-	ns	Input
DSI-Dn+/-	THS-TRAIL	Time to drive flipped differential state after last payload data bit of a HS transmission burst	60+4xUI	-	-	ns	Input
High Speed Mode to/from Low Power Mode Timing							
DSI-CLK+/-	TCLK-PO	Time that the MPU shall	60+52xUI	-	-	ns	Input



Clock lanes- High Speed Mode to/from Low Power Mode Timing

7.3. Reset Input Timing



(VDDI=1.7~1.9V, VCI=3.0 to 3.6V, GND=0V,Ta = -30 to 70°C)

Signal	Symbol	Parameter	MIN	TYP	MAX	Unit	Description
RESX	tRESW	Reset "L" pulse width (Note 1)	10	-	-	µs	
	tREST	Reset complete time (Note 2)	-	-	5	ms	When reset applied during Sleep In Mode
			-	-	120	ms	When reset applied during Sleep Out Mode and Note 5

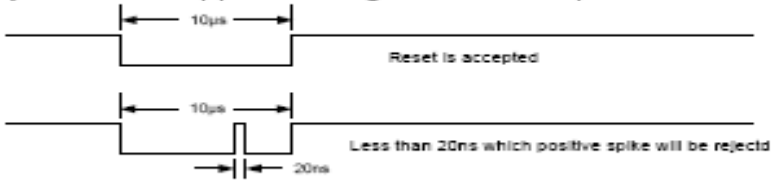
Note 1) Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below.

RESX Pulse	Action
Shorter than 5µs	Reset Rejected
Longer than 10µs	Reset
Between 5µs and 10µs	Reset Start

Note 2) During the resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In–mode) and then return to Default condition for H/W reset.

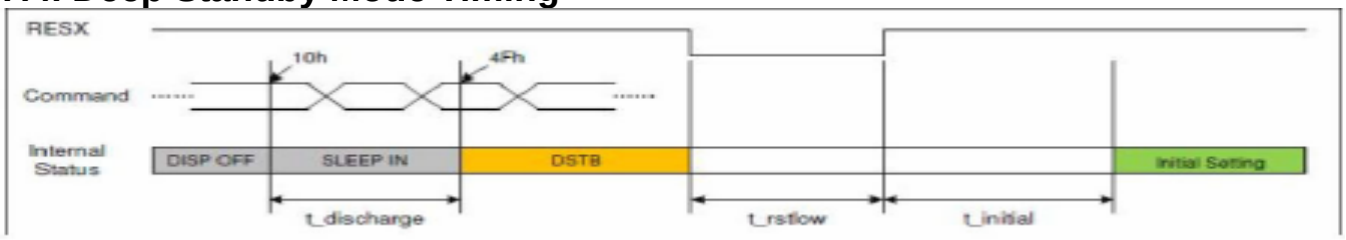
Note 3) During Reset Complete Time, values in OTP memory will be latched to internal register during this period. This loading is done every time when there is H/W reset complete time (t_{REST}) within 5ms after a rising edge of RESX.

Note 4) Spike Rejection also applies during a valid reset pulse as shown below:



Note 5) It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec

7.4. Deep Standby Mode Timing



(*VDDI=1.7~1.9V, VCI=3.0 to 3.6V, GND=0V,* Ta = -30 to 70°C)

Signal	Symbol	Parameter	MIN	TYP	MAX	Unit	Description
RESX	tdischarge	Sleep in into DSTB delay time	-	-	100	ms	
	trstlow	Reset low pulse	3	-	-	ms	
	tinitial	Reset high to initial setting delay time	-	-	120	ms	

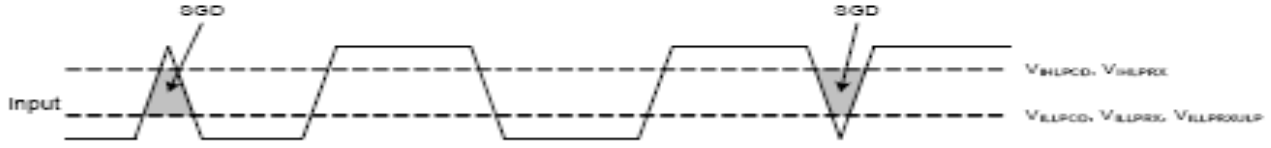
Note 1) t_discharge suggested delay time over 100ms.
Note 2) t_initial suggested delay time over 120ms..

7.5. DC Electrical Characteristics

7.5.1. DC Characteristics for DSI LP Mode

Parameter	Symbol	Conditions	Specification			UNIT
			MIN	TYP	MAX	
Logic high level input voltage	V_{IHLPCD}	LP-CD	450	-	1350	mV
Logic low level input voltage	V_{ILLPCD}	LP-CD	0	-	200	mV
Logic high level input voltage	V_{IHLPRX}	LP-RX (CLK, D0, D1)	880	-	1350	mV
Logic low level input voltage	V_{ILLPRX}	LP-RX (CLK, D0, D1)	0	-	550	mV
Logic low level input voltage	$V_{ILLPRXULP}$	LP-RX (CLK ULP mode)	0	-	300	mV
Logic high level output voltage	V_{OHLPTX}	LP-TX (D0)	1.1	-	1.3	V
Logic low level output voltage	V_{OLLPTX}	LP-TX (D0)	-50	-	50	mV
Logic high level input current	I_{IH}	LP-CD, LP-RX	-	-	10	μA
Logic low level input current	I_{IL}	LP-CD, LP-RX	-10	-	-	μA
Input pulse rejection	SGD	DSI-CLK+/-, DSI-Dn+/- (Note 3)	-	-	300	Vps

Note 1) VDDI=1.7~1.9V, VCI=3.0 to 3.6V, GND=0V, Ta=-30 to 70 °C (to +85 °C no damage)
Note 2) DSI high speed is off.
Note 3) Peak interference amplitude max. 200mV and interference frequency min. 450MHz.

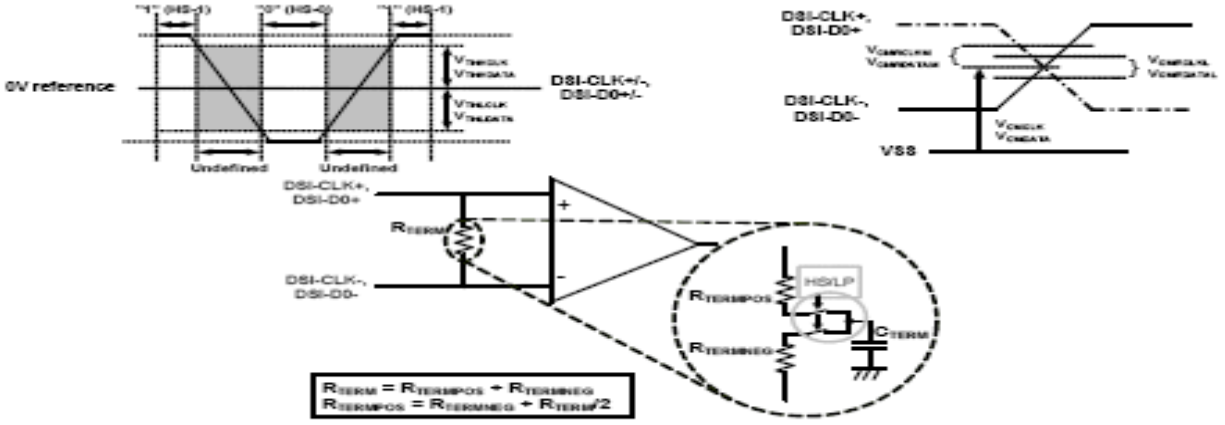


Spike/Glitch rejection-DSI

7.5.2. DC Characteristics for DSI HS Mode

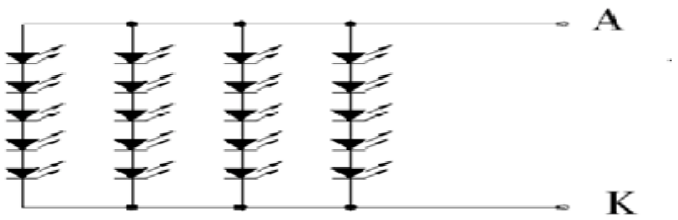
Parameter	Symbol	Conditions	Specification			UNIT
			MIN	TYP	MAX	
Input voltage common mode range	VCMCLK VCMDATA	DSI-CLK+/-, DSI-Dn+/- (Note2, 3)	70	-	330	mV
Input voltage common mode variation (≤ 450MHz)	VCMRCLKL VCMRDATAL	DSI-CLK+/-, DSI-Dn+/- (Note 4)	-50	-	50	mV
Input voltage common mode variation (≥ 450MHz)	VCMRCLKM VCMRDATAM	DSI-CLK+/-, DSI-Dn+/-	-	-	100	mV
Low-level differential input voltage threshold	VTHLCLK VTHLDATA	DSI-CLK+/-, DSI-Dn+/-	-70	-	-	mV
High-level differential input voltage threshold	VTHHCLK VTHHDATA	DSI-CLK+/-, DSI-Dn+/-	-	-	70	mV
Single-ended input low voltage	VILHS	DSI-CLK+/-, DSI-Dn+/- (Note 3)	-40	-	-	mV
Single-ended input high voltage	VIHHS	DSI-CLK+/-, DSI-Dn+/- (Note 3)	-	-	460	mV
Differential input termination resistor	RTERM	DSI-CLK+/-, DSI-Dn+/-	80	100	125	Ω
Single-ended threshold voltage for termination enable	VTERM-EN	DSI-CLK+/-, DSI-Dn+/-	-	-	450	mV
Termination capacitor	CTERM	DSI-CLK+/-, DSI-Dn+/-	-	-	14	pF

Note 1) VDDI=1.7~1.9V, VCI=3.0 to 3.6V, GND=0V, Ta=-30 to 70 °C (to +85 °C no damage).
Note 2) Includes 50mV (-50mV to 50mV) ground difference.
Note 3) Without VCMRCLKM / VCMRDATAM.
Note 4) Without 50mV (-50mV to 50mV) ground difference.
Note 5) Dn=D0, D1, D2 and D3.



Differential voltage range, termination resistor and Common mode voltage

8. Backlight Characteristic



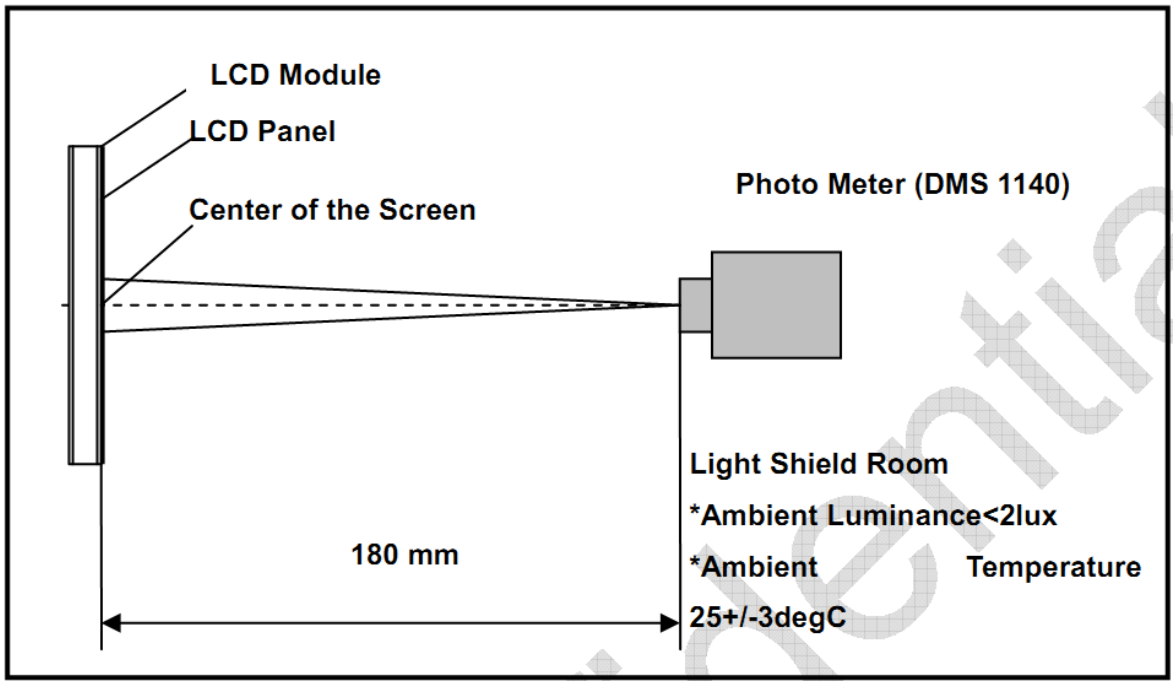
LED Circuit diagram (5 channeling x4 Tied for)

Item	Symbol	MIN	TYP	MAX	UNIT	Test Condition
Supply Voltage	VF	14	15.5	17.5	V	If=80mA
Supply Current	If		80	100	mA	-
Luminous Intensity for LCM	-	300	350	-	Cd/m^2	If=80mA
Uniformity for LCM	-	75	80	-	%	If=80mA
Life Time	20000		-	-	Hr	If=80mA
Backlight Color	White					

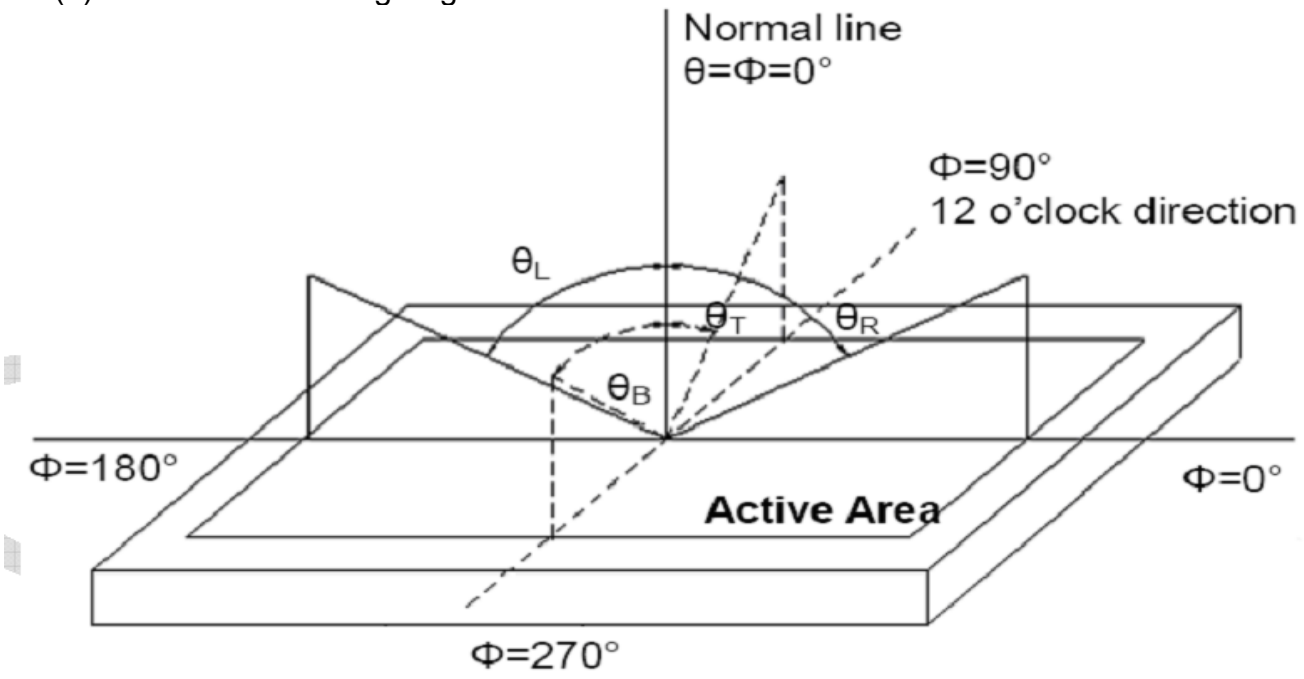
9. Optical Characteristics

Item	Conditions		Min.	Typ.	Max.	Unit	Note
Viewing Angle (CR>10)	Horizontal	θ_L	70	85	-	degree	(1),(2),(6)
		θ_R	70	85	-		
	Vertical	θ_T	70	85	-		
		θ_B	70	85	-		
Contrast Ratio	Center		600	800	-	-	(1),(3),(6)
LCM Luminance	Center point		300	350	-	Cd/m^2	
Response Time	TON		-	11	14	msec	(1),(4),(6)
	TOFF			9	11	msec	
CF Color Chromaticity (CIE1931)	Red x			TBD		-	(1), (6)
	Red y			TBD		-	
	Green x			TBD		-	
	Green y			TBD		-	
	Blue x			TBD		-	
	Blue y			TBD		-	
	White x			TBD		-	
	White y			TBD		-	
NTSC	CIE1931		45	60	-	%	(1),(6)
Transmittance	-		-	4.13	-	%	(1),(5),(6)

Note (1) Measurement Setup: The LCD module should be stabilized at given temp. 25°C for 15 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting backlight for 15 minutes in a windless room.



Note (2) Definition of Viewing Angle



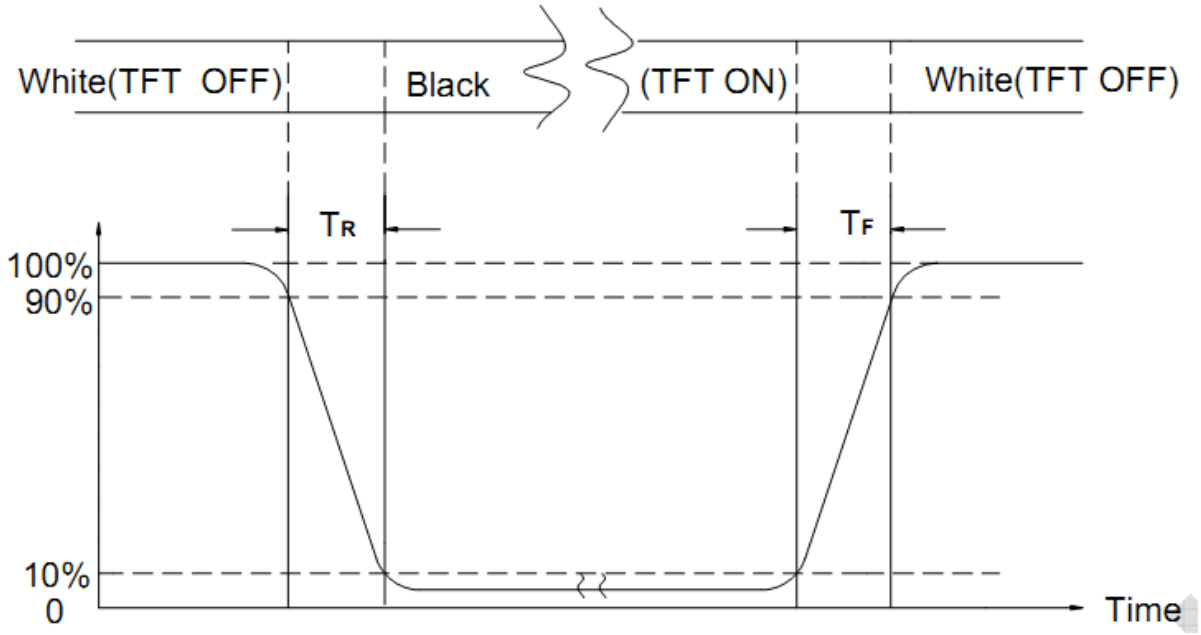
Note (3) Definition of Contrast Ratio (CR)

The contrast ratio can be calculated by the following expression

Contrast Ratio (CR) = L63 / L0

L63: Luminance of gray level 63, L0: Luminance of gray level 0

Note (4) Definition of response time



Note (5) Definition of Transmittance (Module is without signal input)

Transmittance = Center Luminance of LCD / Center Luminance of Back Light x 100%

Note (6) Definition of color chromaticity (CIE1931)

Color coordinates measured at the center point of LCD

10. Reliability Test Conditions and Methods

NO.	TEST ITEMS	TEST CONDITION	INSPECTION AFTER TEST
□	High Temperature Storage	80°C±2°C×200Hours	Inspection after 2~4hours storage at room temperature, the samples should be free from defects: 1, Air bubble in the LCD. 2, Seal leak. 3, Non-display. 4, Missing segments. 5, Glass crack. 6, Current IDD is twice higher than initial value. 7, The surface shall be free from damage. 8, The electric characteristic requirements shall be satisfied.
□	Low Temperature Storage	-30°C±2°C×200Hours	
□	High Temperature Operating	70°C±2°C×120Hours	
□	Low Temperature Operating	-20°C±2°C×120Hours	
□	Temperature Cycle(Storage)	-20°C ⟺ 25°C ⟺ 70°C (30min) (5min) (30min) 1cycle Total 10cycle	
□	Damp Proof Test (Storage)	50°C±5°C×90%RH×120Hours	
□	Vibration Test	Frequency:10Hz~55Hz~10Hz Amplitude:1.5M X,Y,Z direction for total 3hours (Packing Condition)	
□	Drooping Test	Drop to the ground from 1M height one time every side of carton. (Packing Condition)	
□	ESD Test	Voltage:±8KV,R:330Ω,C:150PF,Air Mode,10times	

REMARK:
1, The Test samples should be applied to only one test item.
2, Sample side for each test item is 5~10pcs.
3,For Damp Proof Test, Pure water(Resistance＞10MΩ)should be used.
4,In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judge as a good part.
5, EL evaluation should be accepted from reliability test with humidity and temperature: Some defects such as black spot/blemish can happen by natural chemical reaction with humidity and Fluorescence EL has.
6, Failure Judgment Criterion: Basic Specification Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.

11. Inspection Standard

11.1. QUALITY :

THE QUALITY OF GOODS SUPPLIED TO PURCHASER SHALL COME UP TO THE FOLLOWING STANDARD.

11.1.1. THE METHOD OF PRESERVING GOODS

AFTER DELIVERY OF GOODS FROM AMSON TO PURCHASER. PURCHASER SHALL CONTROL THE LCM AT -10℃ TO 40℃ ,AND IT MIGHT BE DESIRABLE TO KEEP AT THE NORMAL ROOM TEMPERATURE AND HUMIDITY UNTIL INCOMING INSPECTION OR THROWING INTO PROCESS LINE.

11.1.2. INCOMING INSPECTION

(A) THE METHOD OF INSPECTION

IF PURCHASER MAKE AN INCOMING INSPECTION , A SAMPLING PLAN SHALL BE APPLIED ON THE CONDITION THAT QUALITY OF ONE DELIVERY SHALL BE REGARDED AS ONE LOT.

(B) THE STANDARD OF QUALITY

ISO-2859-1 (SAME AS MIL-STD-105E) , LEVEL Ⅱ SINGLE PLAN.

CLASS	AQL(%)
CRITICAL	0.4 %
MAJOR	0.65 %
MINOR	1.5 %
TOTAL	1.5 %

EVERY ITEM SHALL BE INSPECTED ACCORDING TO THE CLASS.

(C) MEASURE

IF AS THE RESULT OF ABOVE RECEIVING INSPECTION , A LOT OUT IS DISCOVERED. PURCHASER SHALL BE INFORM SELLER OF IT WITHIN SEVEN DAYS. BUT FIRST SHIPMENT WITHIN FOURTEEN DAYS.

11.1.3. WARRANTY POLICY

AMSON WILL PROVIDE ONE-YEAR WARRANTY FOR THE PRODUCTS ONLY IF UNDER SPECIFICATION OPERATING CONDITIONS. AMSON WILL REPLACE NEW PRODUCTS FOR THESE DEFECT PRODUCTS WHICH UNDER WARRANTY PERIOD AND BELONG TO THE RESPONSIBILITY OF AMSON.

11.2. CHECKING CONDITION

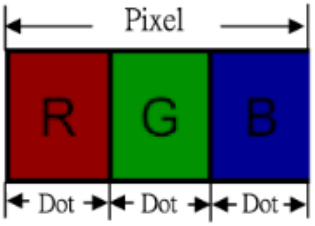
11.2.1.CHECKING DIRECTION SHALL BE IN THE 45 DEGREE AREA TO FACE THE SAMPLE.

11.2.2.CHECKER SHALL SEE OVER 300±25 mm. WITH BARE EYES FAR FROM SAMPLE AND USING 2 PCS. OF 20W FLUORESCENT LAMP.

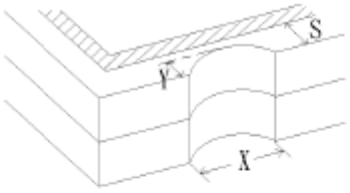
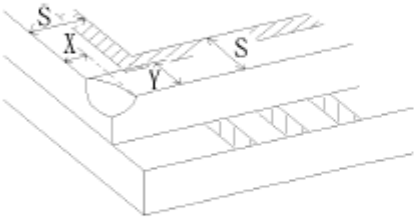
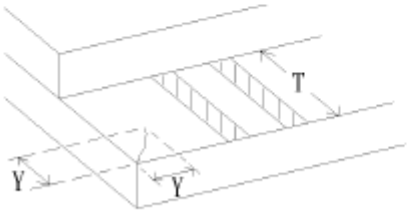
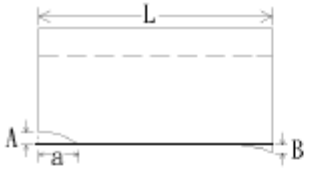
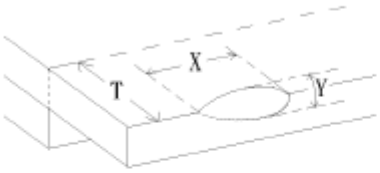
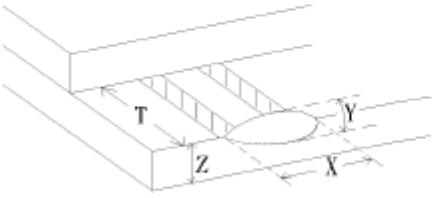
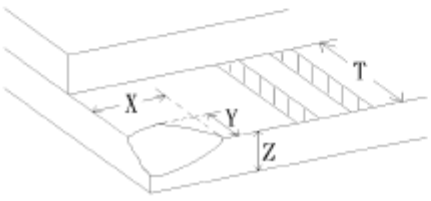
11.3. INSPECTION PLAN :

CLASS	ITEM	JUDGEMENT	CLASS
PACKING & INDICATE	1. OUTSIDE AND INSIDE PACKAGE	"MODEL NO." , "LOT NO." AND "QUANTITY" SHOULD INDICATE ON THE PACKAGE.	Minor
	2. MODEL MIXED AND QUANTITY	OTHER MODEL MIXED.....REJECTED QUANTITY SHORT OR OVER.....REJECTED	Critical
	3. PRODUCT INDICATION	"MODEL NO." SHOULD INDICATE ON THE PRODUCT	Major
ASSEMBLY	4. DIMENSION, LCD GLASS SCRATCH AND SCRIBE DEFECT.	ACCORDING TO SPECIFICATION OR DRAWING.	Major
APPEARANCE	5. VIEWING AREA	POLARIZER EDGE OR LCD'S SEALING LINE IS VISABLE IN THE VIEWING AREA .....REJECTED	Minor
	6. BLEMISH、BLACK SPOT、 WHITE SPOT IN THE LCD AND LCD GLASS CRACKS	ACCORDING TO STANDARD OF VISUAL INSPECTION(INSIDE VIEWING AREA)	Minor
	7. BLEMISH、BLACK SPOT WHITE SPOT AND SCRATCH ON THE POLARIZER	ACCORDING TO STANDARD OF VISUAL INSPECTION(INSIDE VIEWING AREA)	Minor
	8. BUBBLE IN POLARIZER	ACCORDING TO STANDARD OF VISUAL INSPECTION(INSIDE VIEWING AREA)	Minor
	9. LCD'S RAINBOW COLOR	STRONG DEVIATION COLOR (OR NEWTON RING) OF LCD.....REJECTED. OR ACCORDING TO LIMITED SAMPLE (IF NEEDED, AND INSIDE VIEWING AREA)	Minor
ELECTRICAL	10. ELECTRICAL AND OPTICAL CHARACTERISTICS (CONTRAST、VOP、 CHROMATICITY ... ETC)	ACCORDING TO SPECIFICATION OR DRAWING . (INSIDE VIEWING AREA)	Critical
	11.MISSING LINE	MISSING DOT、LINE、CHARACTER ....REJECTED	Critical
	12.SHORT CIRCUIT、 WRONG PATTERN DISPLAY	NO DISPLAY、WRONG PATTERN DISPLAY、CURRENT CONSUMPTION OUT OF SPECIFICATION..... REJECTED	Critical
	13. DOT DEFECT (FOR COLOR AND TFT)	ACCORDING TO STANDARD OF VISUAL INSPECTION	Minor

11.4. STANDARD OF VISUAL INSPECTION

<table>
<tr><th>NO.</th><th>CLASS</th><th>ITEM</th><th>JUDGEMENT</th></tr>
<tr><td>11.4.1</td><td>MINOR</td><td>BLACK AND WHITE SPOT
FOREIGN MATERIEL
DUST IN THE CELL
BLEMISH
SCRATCH</td><td>(A) ROUND TYPE: unit : mm.
<table>
<tr><th>DIAMETER (mm.)</th><th>ACCEPTABLE Q'TY</th></tr>
<tr><td>Φ ≦ 0.1</td><td>DISREGARD</td></tr>
<tr><td>0.1 < Φ ≦ 0.25</td><td>3 (Distance>5mm)</td></tr>
<tr><td>0.25 < Φ</td><td>0</td></tr>
</table>
NOTE: Φ=(LENGTH+WIDTH)/2
(B) LINEAR TYPE: unit : mm.
<table>
<tr><th>LENGTH</th><th>WIDTH</th><th>ACCEPTABLE Q'TY</th></tr>
<tr><td>------</td><td>W ≦0.03</td><td>DISREGARD</td></tr>
<tr><td>L ≦ 5.0</td><td>0.03 < W ≦0.07</td><td>3 (Distance>5mm)</td></tr>
<tr><td>------</td><td>0.07 < W</td><td>FOLLOW ROUND TYPE</td></tr>
</table></td></tr>
<tr><td>11.4.2</td><td>MINOR</td><td>BUBBLE IN POLARIZER
DENT ON POLARIZER</td><td>unit : mm.
<table>
<tr><th>DIAMETER</th><th>ACCEPTABLE Q'TY</th></tr>
<tr><td>Φ ≦ 0.2</td><td>DISREGARD</td></tr>
<tr><td>0.2 < Φ ≦ 0.5</td><td>2 (Distance>5mm)</td></tr>
<tr><td>0.5 < Φ</td><td>0</td></tr>
</table></td></tr>
<tr><td>11.4.3</td><td>MINOR</td><td>Dot Defect</td><td>
<table>
<tr><th>Items</th><th>ACC. Q'TY</th></tr>
<tr><td>Bright dot</td><td>N≦ 4</td></tr>
<tr><td>Dark dot</td><td>N≦ 4</td></tr>
</table>
Pixel Define :
 

Note 1: The definition of dot: The size of a defective dot over 1/2 of whole dot is regarded as one defective dot.
Note 2: Bright dot: Dots appear bright and unchanged in size in which LCD panel is displaying under black pattern.
Note 3: Dark dot: Dots appear dark and unchanged in size in which LCD panel is displaying under pure red, green ,blue pattern.</td></tr>
</table>

NO.	CLASS	ITEM	JUDGEMENT
11.4.4	MINOR	LCD GLASS CHIPPING	 Y > S Reject
11.4.5	MINOR	LCD GLASS CHIPPING	 X or Y > S Reject
11.4.6	MAJOR	LCD GLASS GLASS CRACK	 Y > (1/2) T Reject
11.4.7	MAJOR	LCD GLASS SCRIBE DEFECT	 1. a> L/3 , A>1.5mm. Reject 2. B : ACCORDING TO DIMENSION
11.4.8	MINOR	LCD GLASS CHIPPING (ON THE TERMINAL AREA)	 Φ= (x+y)/2 > 2.5 mm Reject
11.4.9	MINOR	LCD GLASS CHIPPING (ON THE TERMINAL SURFACE)	 Y > (1/3) T Reject
11.4.10	MINOR	LCD GLASS CHIPPING	 Y > T Reject

12. Handling Precautions

12.1. Mounting method

The LCD panel of AMSON TFT module consists of two thin glass plates with polarizes which easily be damaged. And since the module in so constructed as to be fixed by utilizing fitting holes in the printed circuit board.

Extreme care should be needed when handling the LCD modules.

12.2. Caution of LCD handling and cleaning

When cleaning the display surface, Use soft cloth with solvent

[Recommended below] and wipe lightly

- Isopropyl alcohol
- Ethyl alcohol

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Aromatics

Do not wipe ITO pad area with the dry or hard materials that will damage the ITO patterns

Do not use the following solvent on the pad or prevent it from being contaminated:

- Soldering flux
- Chlorine (Cl) , Sulfur (S)

If goods were sent without being silicon coated on the pad, ITO patterns could be damaged due to the corrosion as time goes on.

If ITO corrosion happen by miss-handling or using some materials such as Chlorine (Cl), Sulfur (S) from customer, Responsibility is on customer.

12.3. Caution against static charge

The LCD module use C-MOS LSI drivers, so we recommended that you:

Connect any unused input terminal to power or ground, do not input any signals before power is turned on, and ground your body, work/assembly areas, and assembly equipment to protect against static electricity.

12.4. packing

- Module employs LCD elements and must be treated as such.
- Avoid intense shock and falls from a height.
- To prevent modules from degradation, do not operate or store them exposed direct to sunshine or high temperature/humidity

12.5. Caution for operation

- It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life.
- An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.
- Response time will be extremely delayed at lower temperature then the operating temperature range and on the other hand at higher temperature LCD's how dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operation temperature.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- Slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the maximum operating temperature, 50%Rh or less is required.

12.6. storing

In the case of storing for a long period of time for instance, for years for the purpose or replacement use, the following ways are recommended.

- Storage in a polyethylene bag with the opening sealed so as not to enter fresh air outside in it. And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light's keeping the storage temperature range.
- Storing with no touch on polarizer surface by the anything else.
  [It is recommended to store them as they have been contained in the inner container at the time of delivery from us.

12.7. Safety

- It is recommendable to crash damaged or unnecessary LCD's into pieces and wash off liquid crystal by either of solvents such as acetone and ethanol, which should be burned up later.
- When any liquid leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

13. Precaution for Use

13.1.

A limit sample should be provided by the both parties on an occasion when the both parties agreed its necessity. Judgment by a limit sample shall take effect after the limit sample has been established and confirmed by the both parties.

13.2.

On the following occasions, the handing of problem should be decided through discussion and agreement between responsible of the both parties.

- When a question is arisen in this specification.
- When a new problem is arisen this is not specified in this specification.
- When an inspection specifications change or operating condition change in customer is reported to AMSON TFT and some problem is arisen in this specification due to the change.
- When a new problem is arisen at the customer's operating set for sample evaluation in the customer site.

14. Packing Method

TBD